Part Number:	**0736423209**
Status:	**Active**
Overview:	hdm
Description:	2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 144 Circuits

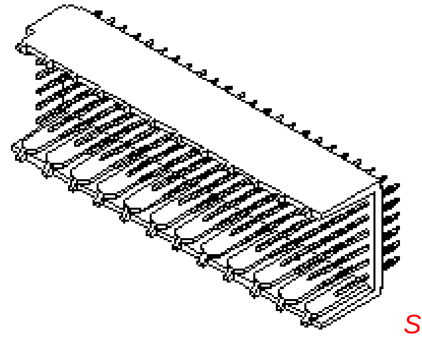
Documents:
Drawing (PDF)
Product Specification PS-73670-9999 (PDF)
RoHS Certificate of Compliance (PDF)

General

Product Family	Backplane Connectors
Series	73642
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.375
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin



Series image - Reference only

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
73642Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Product Specification	PS-73670-9999
Sales Drawing	SD-73642-003

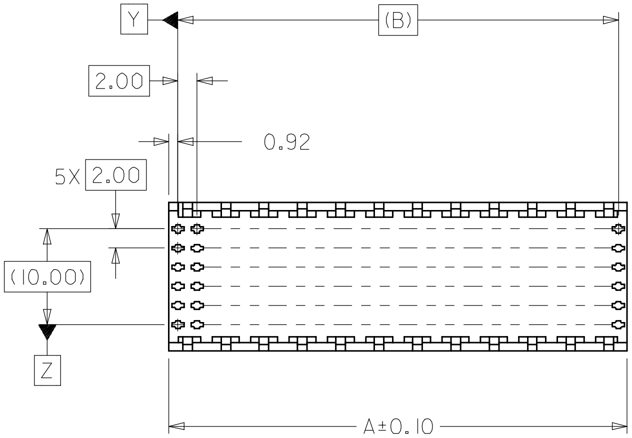
HDM and High Density Metric are trademarks of Amphenol Corporation

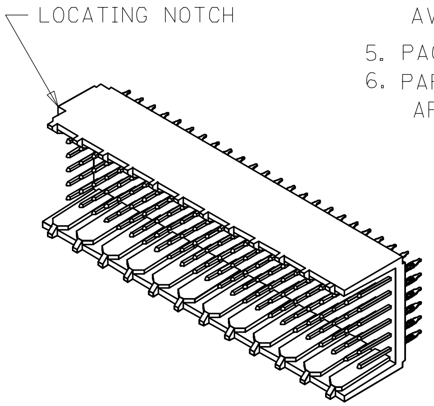
This document was generated on 05/14/2010

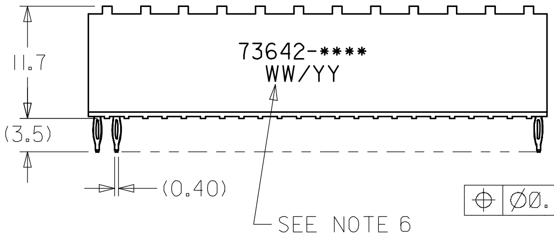
PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

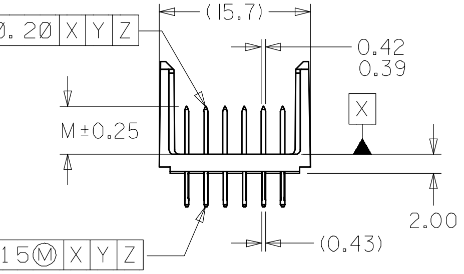
NOTES:

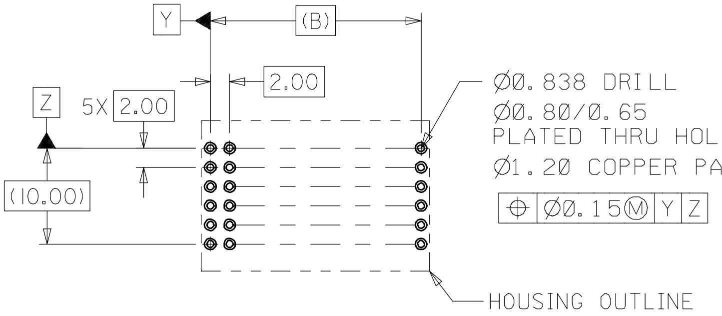
1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK,
   TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA,
   SELECTIVE TIN (Sn) IN TAIL AREA;
   NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.











PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

INITIAL RELEASE
EC NO: UCP2006-1564 2006/01/31
DRWN: JJONIAK 2006/01/31
CH'KD: JBINGHAM 2006/02/02
APPR: CBIXLER
DESCRIPTION
A
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	JJONIAK	2005/11/01
CHECKED BY	JBINGHAM	2005/11/01
APPROVED BY	JBINGHAM	2005/11/01

TITLE
SALES ASSEMBLY LEADFREE
HDM BACKPLANE MODULE
OPEN END OPTION

MOLEX INCORPORATED

MATERIAL NO.: SEE PAGE 2
DOCUMENT NO.: SD-73642-003
SHEET NO.: 1 OF 2
SIZE: B

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	PLATING	DIM "A"	DIM "B"	DIM "M"
73642-2009	72	SELECTIVE GOLD/SELECTIVE TIN	23.84	22.00	5.00
73642-2109	72	SELECTIVE GOLD/SELECTIVE TIN	23.84	22.00	5.50
73642-2209	72	SELECTIVE GOLD/SELECTIVE TIN	23.84	22.00	6.00
73642-3009	144	SELECTIVE GOLD/SELECTIVE TIN	47.84	46.00	5.00
73642-3109	144	SELECTIVE GOLD/SELECTIVE TIN	47.84	46.00	5.50
73642-3209	144	SELECTIVE GOLD/SELECTIVE TIN	47.84	46.00	6.00

INITIAL RELEASE
EC NO: UCP2006-1564
DRWN:JJONIAK 2006/01/31
CH'KD:JBINGHAM 2006/01/31
APPR:CBIXLER 2006/02/02
DESCRIPTION
A
REV

QUALITY SYMBOLS
▼=O
Ⓒ=O

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±---	±---
3 PLACES	±---	±---
2 PLACES	±---	±---
1 PLACE	±---	±---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JJONIAK DATE: 2005/11/01
CHECKED BY: JBINGHAM DATE: 2005/11/01
APPROVED BY: JBINGHAM DATE: 2005/11/01

TITLE
SALES ASSEMBLY LEADFREE HDM BACKPLANE MODULE OPEN END OPTION

molex MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-73642-003
SHEET NO.: 2 OF 2
SIZE: B